

Figure 1

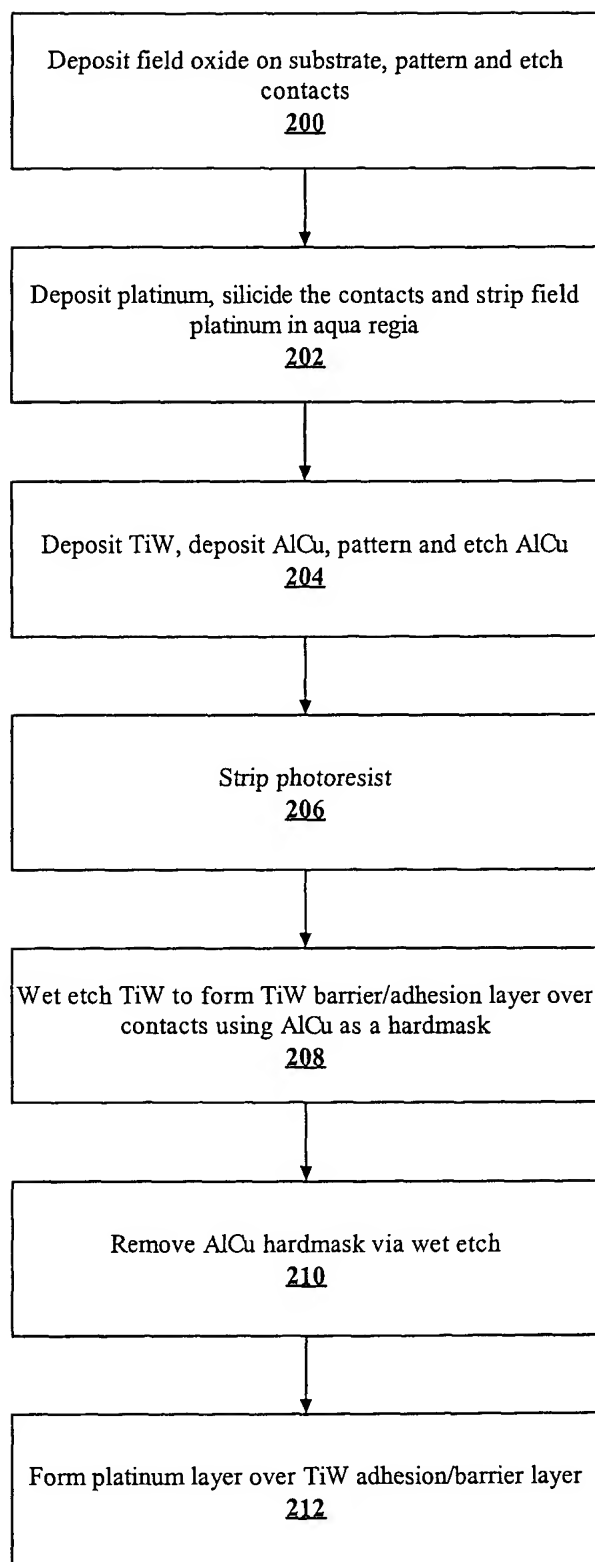


Figure 2

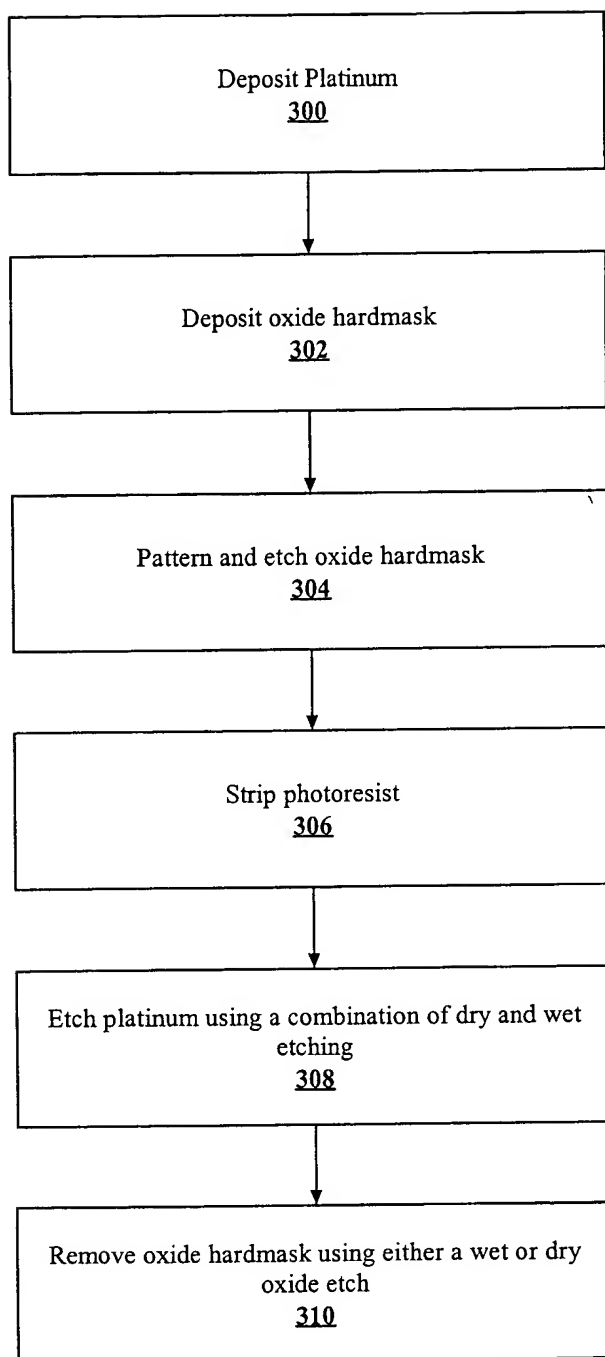


Figure 3

(1)

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Pattern and etch contacts

Strip resist

Deposit Platinum and silicide the contacts

Strip field Pt in aqua regia

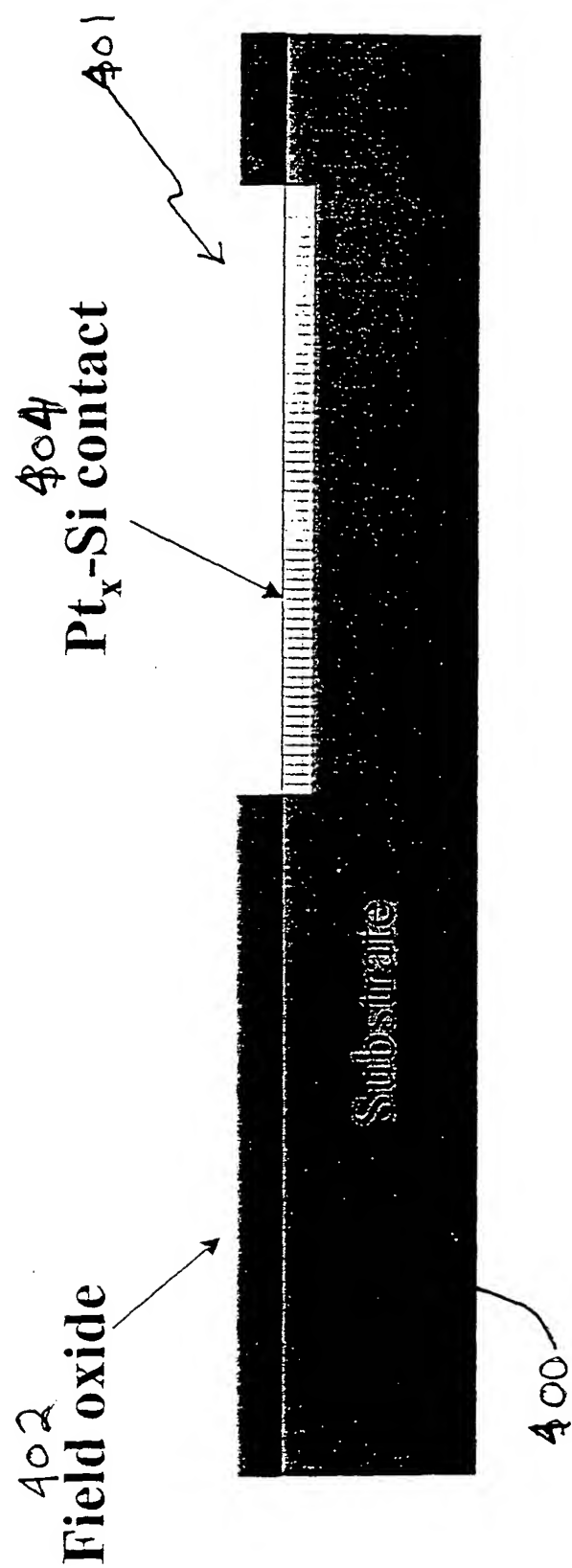


Figure 4a

Deposit TiW

Pattern and etch TiW barrier over contacts

Strip resist

406
TiW

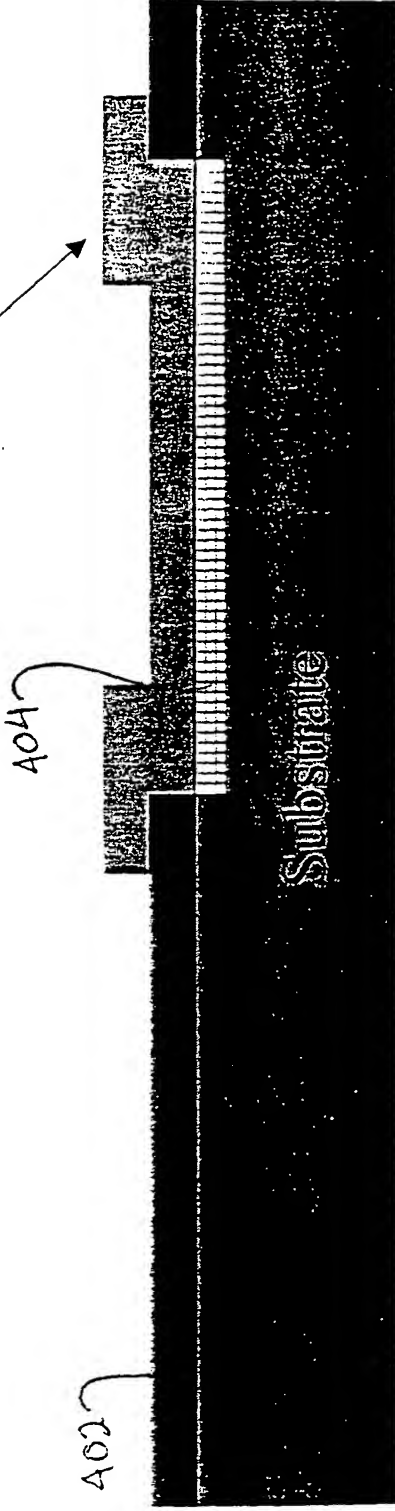


Figure 4b

Note: contingency field on reticle for TiW adhesion layer under all interconnect

201101-60044001

Deposit Platinum for interconnect

Deposit oxide for hardmask

Pattern and etch hardmask

Strip resist

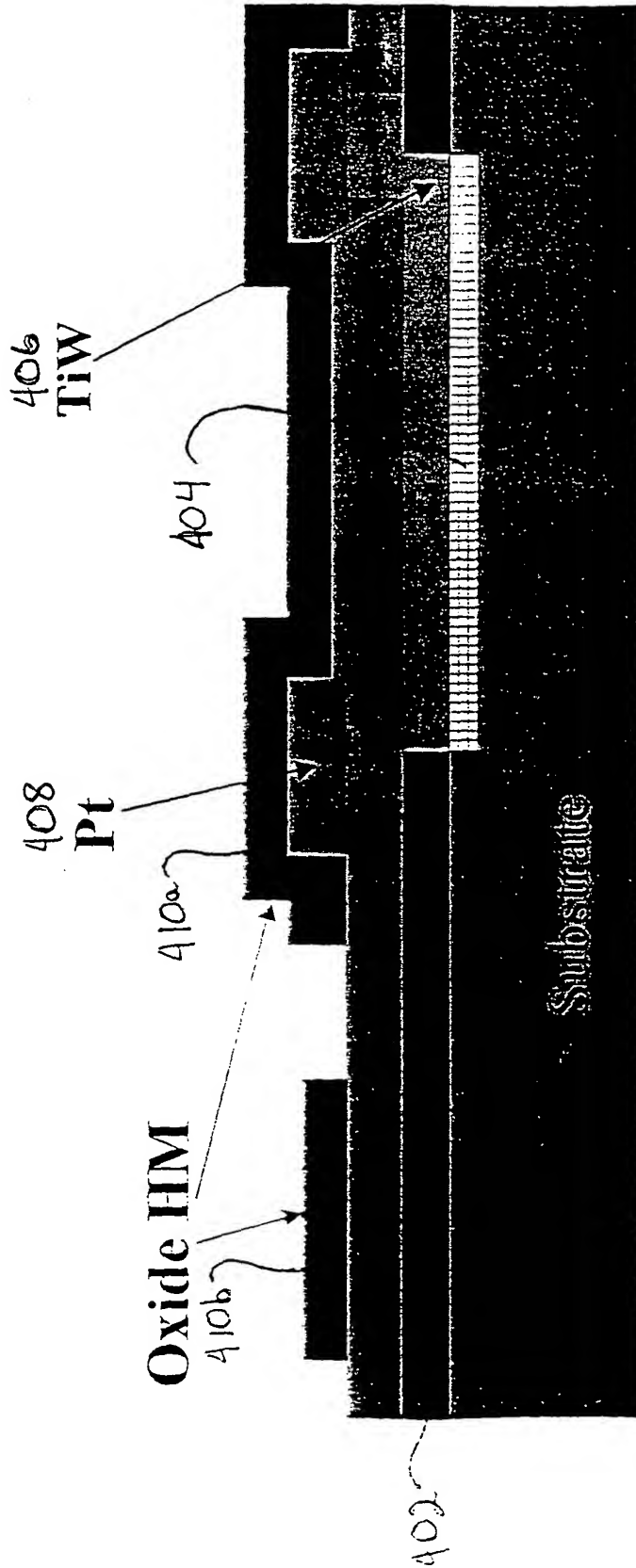


Figure 4c

Etch Platinum for interconnect

Remove hardmask

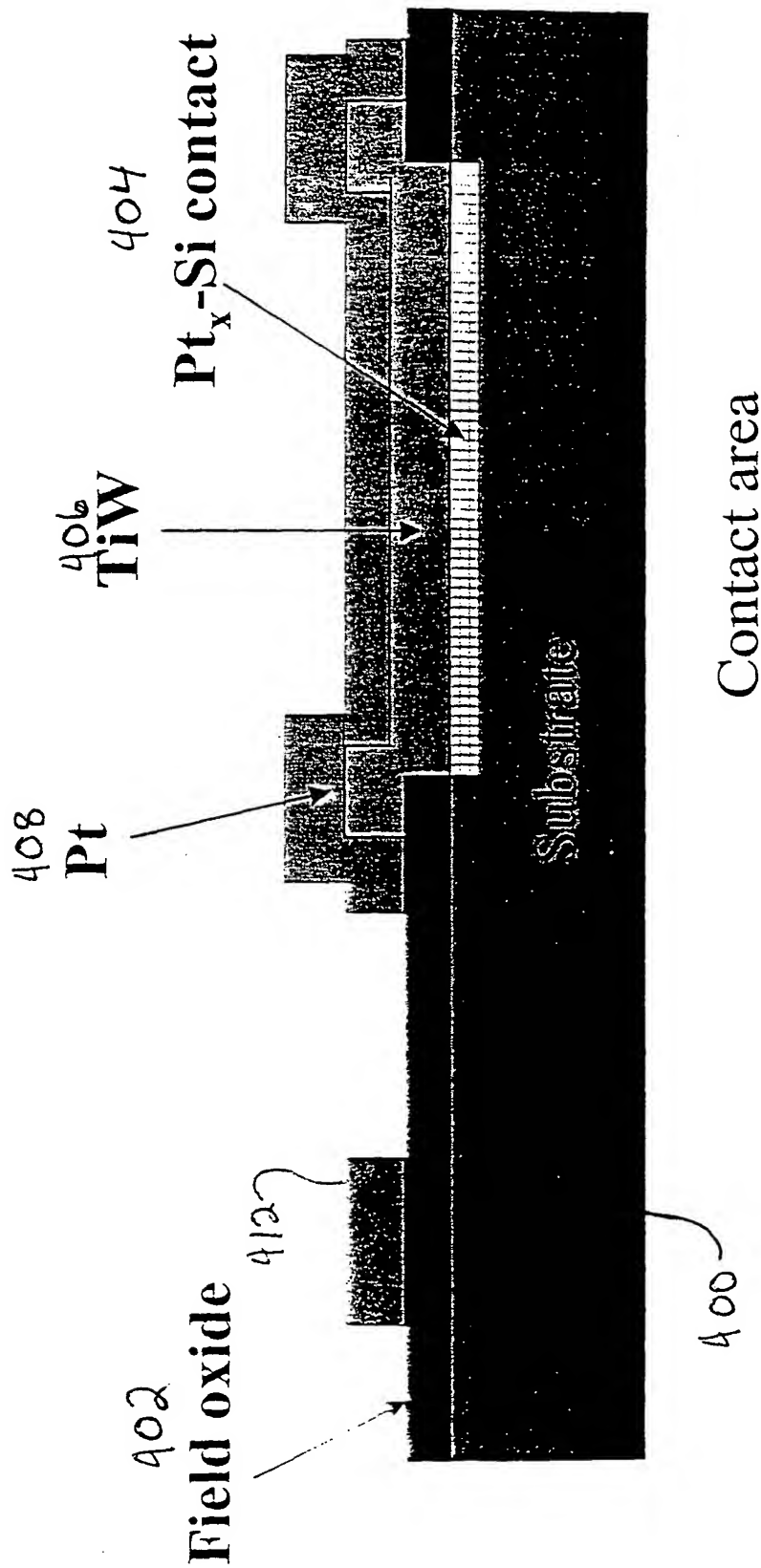


Figure 4d

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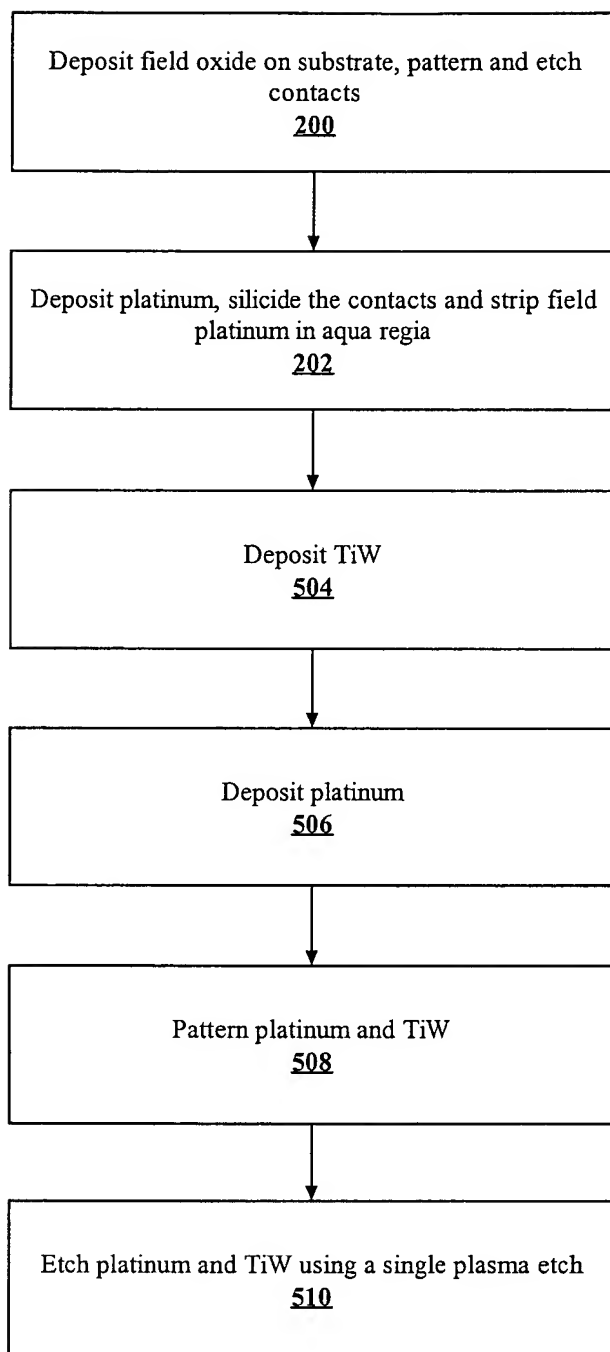


Figure 5

2011FO-60044001

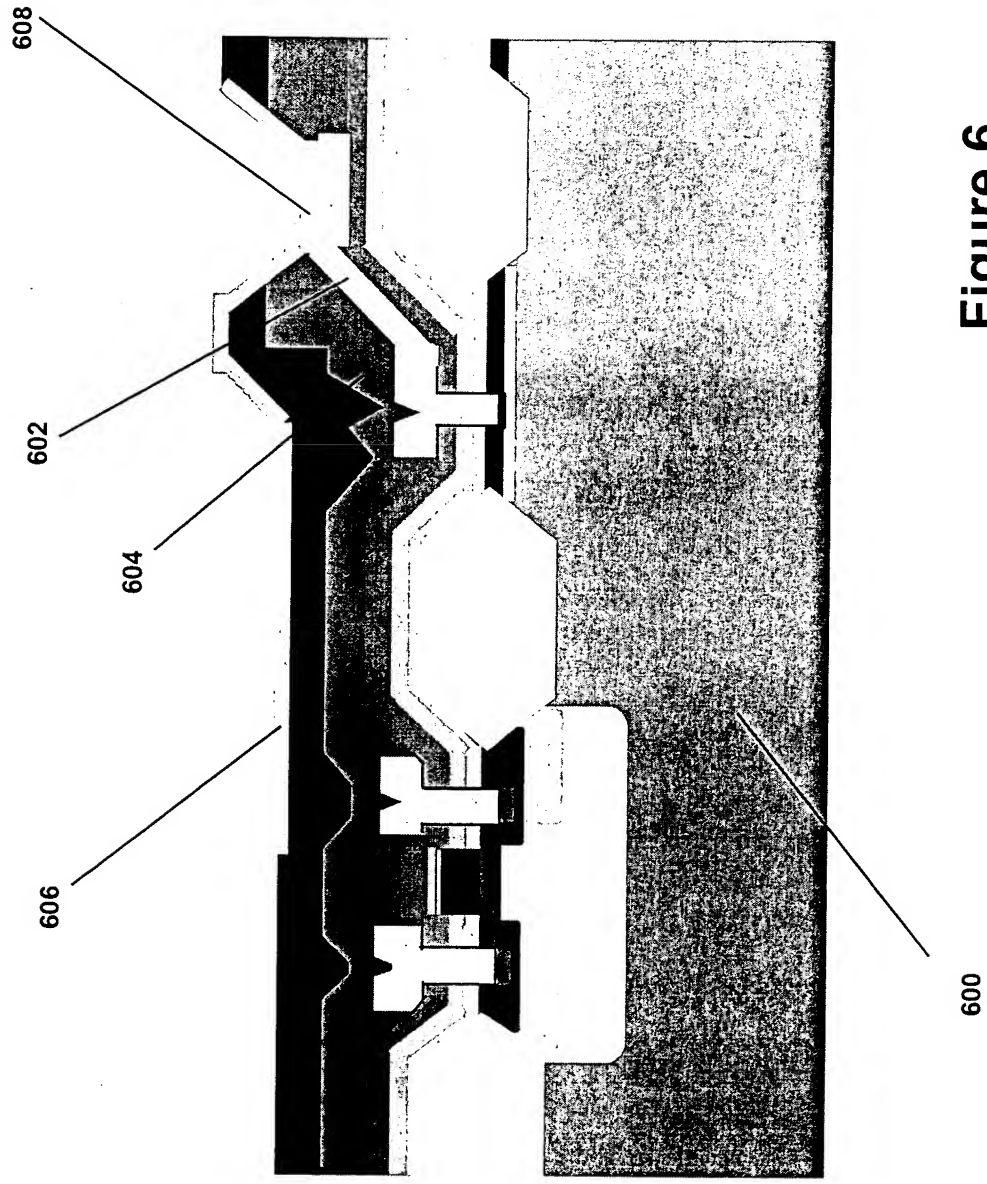


Figure 6